

ZXMN2088DE6

20V Dual SOT23-6 N-channel enhancement mode MOSFET with low gate drive capability

Summary

$V_{(BR)DSS}$	$R_{DS(on)}$ (Ω)	I_D (A)
20	0.200 @ $V_{GS} = 4.5V$	2.1
	0.240 @ $V_{GS} = 2.5V$	1.9
	0.310 @ $V_{GS} = 1.8V$	1.7



Description

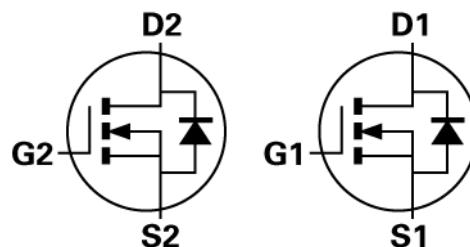
This new generation dual n-channel trench MOSFET from Zetex features low on-resistance achievable with low gate drive.

Features

- Low on-resistance
- Low gate drive capability
- SOT23-6 (dual) package

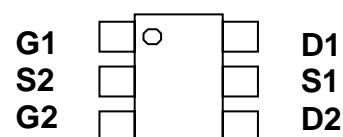
Applications

- Power Management functions
- Disconnect switches
- Relay driving and load switching



Ordering information

Device	Reel size (inches)	Tape width (mm)	Quantity per reel
ZXMN2088DE6TA	7	8	3,000



Pinout – top view

Device marking

2088

Absolute maximum ratings

Parameter	Symbol	Limit	Unit
Drain-Source voltage	V _{DSS}	20	V
Gate-Source voltage	V _{GS}	± 8	V
Continuous Drain current @ V _{GS} = 4.5V; T _A =25°C ^{(b) (d)} @ V _{GS} = 4.5V; T _A =70°C ^{(b) (d)} @ V _{GS} = 4.5V; T _A =25°C ^{(a) (d)}	I _D	2.1 1.7 1.7	A
Pulsed Drain current ^(c)	I _{DM}	8	A
Power dissipation at T _A =25°C ^{(a) (d)}	P _D	0.9	W
Linear derating factor		7.2	mW/°C
Power dissipation at T _A =25°C ^{(a) (e)}	P _D	1.1	W
Linear derating factor		8.8	mW/°C
Power dissipation at T _A =25°C ^{(b) (d)}	P _D	1.3	W
Linear derating factor		10.4	mW/°C
Operating and storage temperature range	T _j , T _{stg}	-55 to +150	°C

Thermal resistance

Parameter	Symbol	Value	Unit
Junction to Ambient ^{(a) (d)}	R _{θJA}	139	°C/W
Junction to Ambient ^{(a) (e)}	R _{θJA}	113	°C/W
Junction to Ambient ^{(b) (d)}	R _{θJA}	96	°C/W

NOTES:

- (a) For a device surface mounted on 25mm x 25mm FR4 PCB with high coverage of single sided 1oz copper, in still air conditions.
- (b) As above measured at t ≤ 5 sec.
- (c) Repetitive rating - 25mm x 25mm FR4 PCB, D=0.02, pulse width 300us – pulse width limited by maximum junction temperature.
- (d) For device with one active die
- (e) For device with two active die running at equal power.

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Electrical characteristics (at $T_{amb} = 25^{\circ}C$ unless otherwise stated).						
Parameter	Symbol	Min.	Typ.	Max.	Unit	Conditions
Static						
Drain-Source breakdown voltage	$V_{(BR)DSS}$	20			V	$I_D = 250\mu A, V_{GS}=0V$
Zero gate voltage drain current	I_{DSS}			100	nA	$V_{DS} = 3V, V_{GS}=0V$
Zero gate voltage drain current	I_{DSS}			1	μA	$V_{DS} = 20V, V_{GS}=0V$
Gate-Body leakage	I_{GSS}			100	nA	$V_{GS}=\pm 8V, V_{DS}=0V$
Gate-Source threshold voltage	$V_{GS(th)}$	0.4		1.0	V	$I_D = 250\mu A, V_{DS}=V_{GS}$
Static Drain-Source on-state resistance (*)	$R_{DS(on)}$		112 137 165	0.200 0.240 0.310	Ω	$V_{GS} = 4.5V, I_D = 1.0A$ $V_{GS} = 2.5V, I_D = 0.6A$ $V_{GS} = 1.8V, I_D = 0.3A$
Forward transconductance (*) (‡)	g_{fs}		4.6		S	$V_{DS} = 10V, I_D = 1.0A$
Dynamic (‡)						
Input capacitance	C_{iss}		279		pF	$V_{DS} = 10V, V_{GS}=0V$ $f=1MHz$
Output capacitance	C_{oss}		52		pF	
Reverse transfer capacitance	C_{rss}		29		pF	
Switching (†) (‡)						
Turn-on-delay time	$t_{d(on)}$		2		ns	$V_{DD} = 10V, V_{GS} = 4.5V$ $I_D = 1A$ $R_G \approx 6.0\Omega$
Rise time	t_r		3.2		ns	
Turn-off delay time	$t_{d(off)}$		12.7		ns	
Fall time	t_f		6.2		ns	
Gate Charge						
Total Gate charge	Q_g		3.8		nC	$V_{DS} = 10V, V_{GS} = 4.5V$ $I_D = 2.4A$
Gate-Source charge	Q_{gs}		0.41		nC	
Gate Drain charge	Q_{gd}		0.56		nC	
Source-drain diode						
Diode forward voltage (‡)	V_{SD}		0.75	0.95	V	$T_j = 25^{\circ}C, I_S = 1.0A, V_{GS} = 0V$
Reverse recovery time	t_{rr}		6.6		ns	$T_j = 25^{\circ}C,$ $I_F = 1.24A$ $di/dt = 100A/\mu s$
Reverse recovery charge	Q_{rr}		1.6		nC	

NOTES:

(*) Measured under pulsed conditions. Pulse width $\leq 300\mu s$; duty cycle $\leq 2\%$.

(†) Switching characteristics are independent of operating junction temperature.

(‡) For design aid only, not subject to production testing.